arrangement in the pad electrodes 11 as one gets near the corner. Accordingly, it is possible to prevent the wires 13 at the corner portion from coming into contact with adjacent wires 13 to thereby produce a short-circuit even when the wire 13 is transformed by the occurrence of wire running or the like. As an example, an Au fine wire or the like having a diameter of approximately 25 μm to 35 μm is used as the bonding wire 13.

IN THE CLAIMS:

Please amend claims 1, 7 and 12 as follows:

1. (amended) A semiconductor device comprising:

a substrate;

a semiconductor chip mounted on one surface of said substrate, said semiconductor chip having an integrated circuit and bonding pads formed on a main surface thereof, said main surface of said semiconductor chip having a quadrilateral shape, said bonding pads being disposed along four sides of said main surface of said semiconductor chip;

a plurality of conductors being disposed on said one surface of said substrate to surround said semiconductor chip along the four sides thereof, said plurality of conductors being arranged so as to extend with one respective end thereof in a radial pattern toward said semiconductor chip;

a plurality of bonding wires electrically connecting said bonding pads with tips of said plurality of conductors, respectively; and

a resin body sealing said semiconductor chip, said plurality of conductors and said plurality of bonding wires;

wherein a pitch between adjacent bonding pads increases in a direction toward four corners defined by the four sides of said main surface of said semiconductor chip.

7. (amended) A semiconductor device comprising:

a substrate;

a semiconductor chip mounted on one surface of said substrate, said semiconductor chip having an integrated circuit and bonding pads formed on a main surface thereof, said main surface of said semiconductor chip having a quadrilateral shape, said bonding pads being disposed along four sides of said main surface of said semiconductor chip;

a plurality of conductors being disposed on said one surface of said substrate to surround said semiconductor chip along the four sides thereof, said conductors being arranged so as to extend with one respective end thereof in a radial pattern toward said semiconductor chip;

a plurality of bonding wires electrically connecting said bonding pads with tips of said conductors respectively; and

a resin body sealing said semiconductor chip and said plurality of bonding wires;

wherein a pitch between first ones of adjacent bonding pads at each of four corners defined by the four sides of said main surface of said semiconductor chip is wider than a pitch between second ones of adjacent bonding pads which are disposed at other than the four corners and at a relatively central position of each of the four sides.

12. (amended) A semiconductor device comprising;

a substrate;

a semiconductor chip mounted on one surface of said substrate, said semiconductor chip having an integrated circuit and bonding pads formed on a main surface thereof, said main surface of said semiconductor chip having a quadrilateral shape, said bonding pads being disposed along four sides of said main surface of